



PART NO. : TG10-DA1NSLF

6PIN SMT ISOLATION MODULE

DESIGNED FOR CIRRUS LOGIC DIGITAL AUDIO
INTERFACE APPLICATIONS

LEAD-FREE/RoHS COMPLIANT

COMPATIBLE TO LEAD-FREE SOLDERING PROCESS
CONDITION PER IPC/JEDEC J-STD-020C

UL/EN60950 AND DEMKO RECOGNIZED

EXTENDED OPERATING TEMPERATURE $-40/+85^{\circ}\text{C}$

ELECTRICAL SPECIFICATIONS @25°C

URNS RATIO

P1-2:P6-5

1:1 $\pm 2\%$

OCL (100KHz,0.1V)

P1-2

750 μH nom

DCR P1-2

0.5 Ω max

LL P1-2

1.0 μH max

Cw/w P1-6

(Ground P3)

18pF max

9pF max

BANDWIDTH (Nominal)

10kHz-200MHz

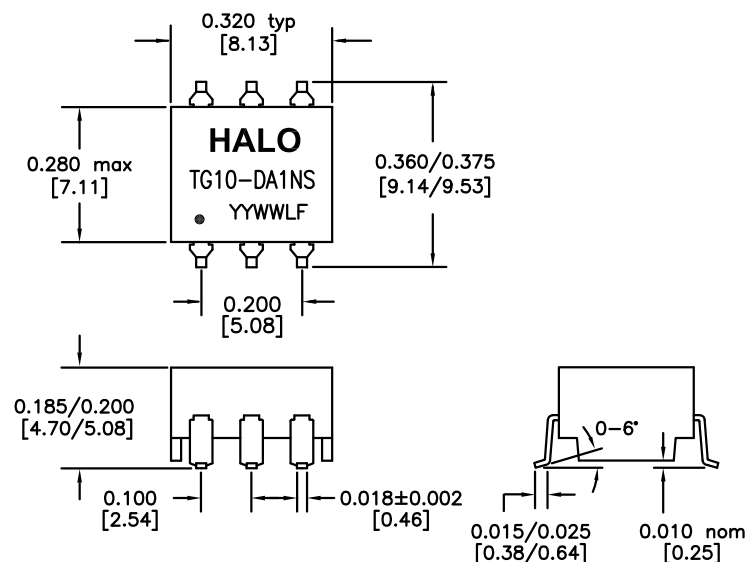
ISOLATION

PRI - SEC

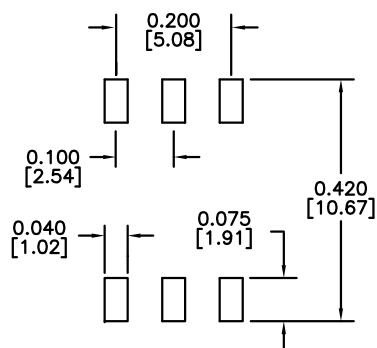
1500Vrms

PRI,SEC - SHIELD

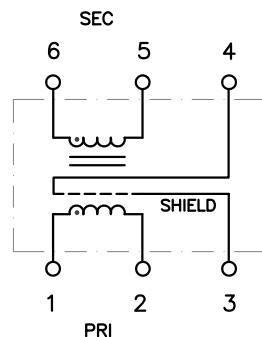
1500Vrms



DIMENSIONS: Inch [mm]
CO-PLANARITY: 0.004 [0.10]
TOLERANCES: ± 0.005 INCH IF NOT SPECIFIED



RECOMMENDED SOLDER PAD DIMENSIONS



ONLY ONE END OF THE
SHIELD CAN BE GROUNDED

HALO/PBL

CALIFORNIA, USA
KOWLOON, HONG KONG
SINGAPORE

TITLE ISOLATION MODULE

FOR CIRRUS LOGIC DIGITAL AUDIO

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SCALE NONE

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SIGNATURES

DRAWN LI ZHI ZHONG

CHECKED LEI KEONG

APPROVED PETER LU

FILE DA1NSLF.DWG

DATE

5/4/16

8/8/16

8/8/16

REV.

A

B

C

D

DESC.

PROD. RELEASE

ADD BW SPEC.

UPDATE

UPDATE DESC.



DATE

5/4/16

5/13/16

5/17/16

8/8/16